

**In the claims:**

The following is a complete listing of all the claims in the application, with an indication of the status of each:

1. (Currently amended) A method for gluing microcomponents to a substrate in the production of microsystem components, comprising ~~the following steps:~~

applying a reactive or nonreactive, pulverulent, hotmelt adhesive ~~to~~ with a result that only selected contact areas on a surface of at least one of a substrate and at least one microcomponent, said hotmelt adhesive not being present on other areas on said surface of said at least one of a substrate and at least one microcomponent; and ~~and/or the substrate; heating the hotmelt adhesive, and~~

applying the at least one microcomponent to the substrate~~[[,]]~~ by melting the hotmelt adhesive ~~being~~ on the contact areas when the hotmelt adhesive is between the at least one microcomponent and the substrate, and bonding ~~wherein said applying step includes areal application of pulverulent hotmelt adhesive to a surface of the substrate or the at least one microcomponent, incipient melting of selected bond sites by local heating by means of irradiation of the selected bondsites through a focusable heat source of a powder layer; removal of the powder layer not incipiently melted; and adhesion of the at least one microcomponent to the substrate~~ during cooling of the hotmelt adhesive below its melting point.

2. (Currently amended) The method of claim 1, wherein said step of applying a reactive or nonreactive, pulverulent, hotmelt adhesive includes the steps of

applying a tape or layer of said hot melt adhesive to said surface of said at least one of a substrate and at least one microcomponent,

heating said tape or layer at regions which correspond to said contact areas to a temperature sufficient to melt said hotmelt adhesive at said retions, wherein said heating takes place selectively with a focusing heat source, and

removing hotmelt adhesive from said surface of said at least one of a substrate and at least one micocomponent in regions which were not heated in said heating step.

3. (Previously presented) The method of claim 1 wherein the hotmelt adhesive is applied as granules.
4. (Currently amended) The method of claim 1 wherein ~~the incipient~~ melting the hotmelt adhesive during the step of applying the at least microcomponent to the substrate is achieved using ~~takes place with~~ a laser as a heat source.
5. (Currently amended) The method of claim 1 ~~further comprising the step of~~ wherein said applying a reactive or nonreactive, pulverulent, hotmelt adhesive is performed by immersing a heated substrate or microcomponent in said ~~pulverulent~~ hotmelt adhesive to apply the adhesive at immersed areas which correspond to said selected contact areas.
6. (Currently amended) The method of claim 1 wherein said applying a reactive or nonreactive, pulverulent, hotmelt adhesive ~~applying~~ step includes application of said ~~pulverulent~~ hotmelt adhesive through a contoured screen to said at least one of the substrate or the at least one microcomponent.
7. (Currently amended) The method of claim 1 further comprising ~~the a~~ step of electrostatic charging of a surface of said at least one of said substrate or said at least one microcomponent and/or said a ~~pulverulent~~ hotmelt adhesive to support either the areal or patterned application of said hotmelt adhesive in said applying a reactive or nonreactive, pulverulent, hotmelt adhesive step.
8. (Currently amended) The method of claim 1 ~~further comprising the step of immersion~~ wherein said applying a reactive or nonreactive, pulverulent, hotmelt adhesive step is performed by immersing of a heated patterned surface of the at least one of a substrate or the at least one microcomponent in ~~pulverulent~~ said hotmelt adhesive to apply the hotmelt adhesive at raised sites on the patterned surface which correspond to said selected contact areas.

9. (Currently amended) The method claim 1 ~~further comprising the step of~~ wherein said step of applying a reactive or nonreactive, pulverulent, hotmelt adhesive includes the steps of electrostatic charging of a roll, and wherein ~~areal~~ application of the ~~pulverulent~~ hotmelt adhesive is made to a partly electrostatically charged surface of the roll, and transferring selected bondsites from the roll to the at least one of the substrate or the at least one microcomponent, and ~~wherein brief heating of the surface of the roll is used to incipiently melt the adhesive, and transferring the hotmelt adhesive to said surface of said at least one of said substrate and said at least one microcomponent.~~
10. (Currently amended) The method of claim 1 further comprising ~~the a~~ step of electrostatic charging of ~~the~~ selected bondsites, and ~~wherein areal application of the pulverulent hotmelt adhesive is performed to~~ wherein application of said hotmelt adhesive in said applying a reactive or nonreactive, pulverulent, hotmelt adhesive step is performed by applying said hotmelt adhesive to a partly electrostatically charged surface of the at least one of the substrate or the at least one microcomponent, and ~~brief heating of the surface is performed to incipiently melt the hotmelt adhesive at the electrostatically charged bondsites.~~
11. (Currently amended) The method of claim 1, further comprising ~~placement of a step of~~ placing a transfer sheet with granular or pulverulent adhesive ~~attaching~~ attached thereto, or of a layer produced from hotmelt adhesive, to ~~the adherend of the~~ at least one of the substrate or at least one microcomponent or substrate.
12. (Currently amended) The method of claim 11, further comprising ~~the a~~ step of contouring of the transfer sheet to selected bondsites.
13. (Currently amended) The method of claim 11, ~~characterized by application of the adhesive to selected bondsites, when the transfer sheet lies on the surface of at least onemicrocomponent or substrate, by~~ further comprising transferring hotmelt adhesive to said

surface by either mechanically stamping the transfer sheet onto the at least one of the substrate or ~~the~~ at least one microcomponent, or by locally heating the transfer sheet.

14. (Currently amended) The method of claim 1 further comprising ~~the~~ a step of preheating of ~~at least surfaces~~ the surface to which hotmelt adhesive is to be applied.

15. (Currently amended) The method of claim 1 further comprising ~~the~~ a step of afterheating of the at least one ~~microsystem component~~ microcomponent after adhering to the substrate.

16. (Currently amended) The method of claim ~~14~~ 15, wherein the afterheating takes place ~~selectively by means of~~ using a focused or global focusing heat source ~~or globally~~.

17. (Currently amended) The method of claim ~~1~~ 3 wherein the granules of the hotmelt adhesive ~~adhesives~~ have a diameter of less than 150  $\mu\text{m}$ .

18. (Currently amended) The method of claim 17, wherein the diameter of the granules is ~~situated~~ in the range from 0.5 to 150  $\mu\text{m}$ .

19. (Currently amended) A microsystem component having at least one microcomponent bonded to a substrate, ~~characterized in that~~ wherein the adhesive bonding is performed by the method of:

applying a ~~reactive or nonreactive hotmelt adhesive to at least one microcomponent and/or the~~ substrate;

~~heating the hotmelt adhesive, and~~

~~applying the at least one microcomponent to the substrate, the hotmelt adhesive being on the contact areas between the at least one microcomponent and the substrate wherein said applying step includes~~

~~areal application of pulverulent hotmelt adhesive to a surface of~~ the at least one of a substrate or ~~the~~ at least one microcomponent,

~~incipient~~ melting of said hotmelt adhesive at selected bond sites on said surface by ~~heating by means of irradiation of~~ irradiating a powder layer on the selected bond sites ~~through~~ using a focusable heat source ~~of a powder layer~~; ~~removal of the powder layer not incipiently melted~~; and adhering the at least one ~~adhesion of the at least one~~ microcomponent to the substrate during cooling of the hotmelt adhesive.

20. (Currently amended) The microsystem component of claim 19, ~~characterized in that~~ wherein the at least one microcomponent is smaller than 1000  $\mu\text{m}$ .

21. (New) The method of claim 6, wherein said hotmelt adhesive is applied as a dispersion.